Dow Electronic Materials Announces Next-Generation KLEBOSOL® II 1630 Dilutable Colloidal Silica Slurry

Strong customer interest based on excellent performance characteristics and reduced cost of consumables

Taipei, Taiwan — September 9, 2010 — Dow Electronic Materials (NYSE:DOW), a leader and innovator in chemical mechanical planarization (CMP) technology for the global semiconductor industry, today announced the availability of the KLEBOSOL® II 1630 Slurry, an advanced, dilutable slurry that combines the best attributes of colloidal and fumed silica slurries. Developed for leading-edge semiconductor manufacturing, the KLEBOSOL® slurry offers a high-performance, low cost of consumables alternative for CMP.

"KLEBOSOL® colloidal silica slurries provide excellent process stability with low defect levels," said Asa Yamada, global slurry marketing director for Dow Electronic Materials. "We are now driving to lower point-of-use (POU) solids levels to improve end user cost of consumables. This new generation of KLEBOSOL® slurries now offers the performance benefits of colloidal silica with the planarization and dilution capabilities typically associated with fumed silicas. We've seen strong interest in this new slurry, with multiple adoptions in high volume manufacturing."

The KLEBOSOL® II 1630 slurry is formulated with elongated fractal colloidal silica particles. It combines the high stability and ease-of-handling properties of colloidal silica with a new morphology that provides fumed-like particle planarization and allows for dilution. This makes KLEBOSOL® II 1630 highly cost competitive while maintaining the performance characteristics of colloidal silica slurries, including excellent removal rate stability, low defectivity, high planarization and tight process control.

The KLEBOSOL® II 1630 slurry offers lower POU solids levels with a 0.3 micron POU filtration capability. It is easy-to-handle and resistant to agglomerate formation under high shear conditions. Additionally, compared to fumed silica, it can significantly extend pad life as end users are able to use less aggressive pad conditioners due to the colloidal silica's low impact on pad surface asperities.

About Dow

Dow combines the power of science and technology with the "Human Element" to passionately innovate what is essential to human progress.

The Company connects chemistry and innovation with the principles of sustainability to help address many of the world's most challenging problems such as the need for clean water, renewable energy generation and conservation, and increasing agricultural productivity.

Dow's diversified industry-leading portfolio of specialty chemical, advanced materials, agrosciences and plastics businesses delivers a broad range of technology-based products and solutions to customers in approximately 160 countries and in high growth sectors such as electronics, water, energy, coatings and agriculture. In 2009, Dow had annual sales of $45 billion and employed approximately 52,000 people worldwide. The Company's more than

5,000 products are manufactured at 214 sites in 37 countries across the globe. References to "Dow" or the "Company" mean The Dow Chemical Company and its consolidated subsidiaries unless otherwise expressly noted. More information about Dow can be found at www.dow.com.

About Dow Electronic Materials

Dow Electronic Materials, a global supplier of materials and technologies to the electronics industry, brings innovative leadership to the semiconductor, interconnect, finishing, photovoltaic, display, LED and optics markets. From advanced technology centers worldwide, teams of talented Dow research scientists and application experts work closely with customers, providing solutions, products and technical service necessary for next-generation electronics. These partnerships energize Dow's power to invent. Its key end-use applications include a broad range of consumer electronics from personal computers, to television monitors, cellular phones, global positioning systems, automobile safety systems, and avionics.

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